

### **Description**

The BSC097N06NS uses advanced trench technology to provide excellent R<sub>DS(ON)</sub>, low gate charge and operation with gate voltages as low as 4.5V. This device is suitable for use as a Battery protection or in other Switching application.

### **General Features**

 $V_{DS} = 60V I_{D} = 65A$ 

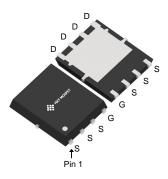
 $R_{DS(ON)} < 11 m\Omega V_{GS} = 10 V$ 

### **Application**

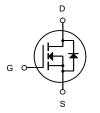
Battery protection

Load switch

Uninterruptible power supply



DFN5X6-8L (TDSON-8-EP(5.1x5.9))



N-Channel MOSFET

### **Package Marking and Ordering Information**

| Product ID  | Pack                               | Marking  | Qty(PCS) |
|-------------|------------------------------------|----------|----------|
| BSC097N06NS | DFN5X6-8L<br>(TDSON-8-EP(5.1x5.9)) | 097N06NS | 5000     |

Absolute Maximum Ratings (T<sub>C</sub>=25<sup>°</sup>Cunless otherwise noted)

| Symbol                               | Parameter  | Rating     | Units |
|--------------------------------------|--|------------|-------|
| Vos                                  | Drain-Source Voltage                             | 60         | V     |
| Vgs                                  | Gate-Source Voltage                              | V          |       |
| I <sub>D</sub> @T <sub>C</sub> =25°C | Continuous Drain Current, V <sub>GS</sub> @ 10V  | А          |       |
| I <sub>D</sub> @T <sub>C</sub> =70°C | Continuous Drain Current, V <sub>GS</sub> @ 10V  | 49         | А     |
| Ірм                                  | Pulsed Drain Current <sup>2</sup>                | 180        | А     |
| EAS                                  | Single Pulse Avalanche Energy <sup>3</sup>       | 56         | mJ    |
| P <sub>D</sub> @T <sub>C</sub> =25°C | Total Power Dissipation <sup>4</sup>             | 89         | W     |
| Тѕтс                                 | Storage Temperature Range                        | -55 to 150 | °C    |
| TJ                                   | Operating Junction Temperature Range -55 to 150  |            | °C    |
| $R_{\theta JA}$                      | Thermal Resistance Junction-Ambient <sup>1</sup> | 62         | °C/W  |



# **Electrical Characteristics** (T<sub>J</sub>=25 °C unless otherwise specified)

| Symbol               | Parameter Test Condition                             |  | Min. | Тур. | Max. | Units |  |
|----------------------|--|--|------|------|------|-------|--|
|                      |  |  |      |      |      |       |  |
| V <sub>(BR)DSS</sub> | Drain-Source Breakdown Voltage                       | V <sub>GS</sub> =0V, I <sub>D</sub> =250µA                   | 60   | -    | -    | V     |  |
| I <sub>DSS</sub>     | Zero Gate Voltage Drain Current                      | V <sub>DS</sub> =60V, V <sub>GS</sub> =0V,                   | -    | -    | 1.0  | μΑ    |  |
| I <sub>GSS</sub>     | Gate to Body Leakage Current                         | V <sub>DS</sub> =0V, V <sub>GS</sub> = ±20V                  | -    | -    | ±100 | nA    |  |
| V <sub>GS(th)</sub>  | Gate Threshold Voltage                               | V <sub>DS</sub> =V <sub>GS</sub> , I <sub>D</sub> =250µA     | 1.0  | 1.6  | 2.5  | V     |  |
| В                    | Static Drain-Source on-Resistance                    | V <sub>GS</sub> =10V, I <sub>D</sub> =20A                    | -    | 8    | 11   |       |  |
| R <sub>DS(on)</sub>  |  | V <sub>GS</sub> =4.5V, I <sub>D</sub> =10A                   | -    | 14   | 20   | mΩ    |  |
| C <sub>iss</sub>     | Input Capacitance                                    | )/ O5)/ )/ O)/   | _    | 930  | -    | pF    |  |
| Coss                 | Output Capacitance                                   | V <sub>DS</sub> =25V, V <sub>GS</sub> =0V,<br>f=1.0MHz       | -    | 370  | -    | pF    |  |
| Crss                 | Reverse Transfer Capacitance                         | 1-1.UIVITZ   | -    | 20   | -    | pF    |  |
| Qg                   | Total Gate Charge                                    | \/ 20\/ L 00A  | -    | 19   | -    | nC    |  |
| Q <sub>gs</sub>      | Gate-Source Charge                                   | $V_{DS}$ =30V, $I_{D}$ =20A, $V_{GS}$ =10V                   | -    | 4.8  | -    | nC    |  |
| $Q_{gd}$             | Gate-Drain("Miller") Charge                          | VGS-10V  | -    | 4.5  | -    | nC    |  |
| t <sub>d(on)</sub>   | Turn-on Delay Time                                   |  | -    | 4.9  | -    | ns    |  |
| t <sub>r</sub>       | Turn-on Rise Time                                    | V <sub>DD</sub> =30V, I <sub>D</sub> =20A,                   | -    | 31   | -    | ns    |  |
| t <sub>d(off)</sub>  | Turn-off Delay Time                                  | R <sub>G</sub> =1.6Ω, V <sub>GS</sub> =10V                   | -    | 23   | -    | ns    |  |
| t <sub>f</sub>       | Turn-off Fall Time                                   |  | -    | 8.7  | -    | ns    |  |
|                      | Maximum Continuous Drain to Source Diode Forward     |  |      |      | G.E. | ^     |  |
| l <sub>S</sub>       | Current  |  |      | _    | 65   | Α     |  |
| I <sub>SM</sub>      | Maximum Pulsed Drain to Source Diode Forward Current |  |      | -    | 240  | Α     |  |
| \/                   | Drain to Source Diode Forward                        | V <sub>GS</sub> =0V, I <sub>S</sub> =30A                     | -    | -    | 1.4  | V     |  |
| V <sub>SD</sub>      | Voltage  | VGS-UV, IS-3UA   |      |      |      |       |  |
| t <sub>rr</sub>      | Body Diode Reverse Recovery Time                     | <br>  T」=25℃,  | -    | 34   | -    | ns    |  |
| Q <sub>rr</sub>      | Body Diode Reverse Recovery                          | I <sub>J</sub> =25 C,<br>  I <sub>F</sub> =20A,dI/dt=100A/μs |      | 14   | -    | nC    |  |
| <b>Q</b> rr          | Charge   | 1-20A,ul/ul-100A/μS  | -    |      |      |       |  |

Notes:1. Repetitive Rating: Pulse Width Limited by Maximum Junction Temperature

- 2. EAS condition:  $T_J$ =25  $^{\circ}$ C,  $V_{DD}$ =30V,  $V_G$ =10V,  $R_G$ =25 $\Omega$ , L=0.5mH,  $I_{AS}$ =12A
- 3. Pulse Test: Pulse Width≤300µs, Duty Cycle≤0.5%



## **Typical Performance Characteristics**

Figure1: Output Characteristics

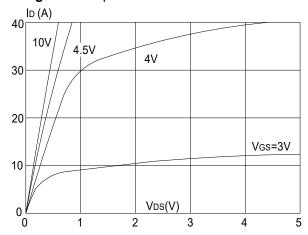


Figure 3:On-resistance vs. Drain Current

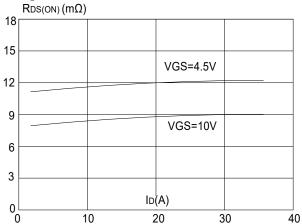


Figure 5: Gate Charge Characteristics

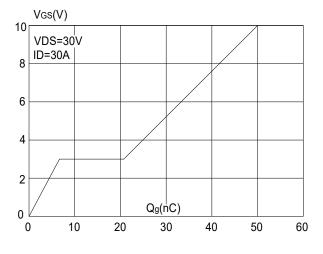


Figure 2: Typical Transfer Characteristics

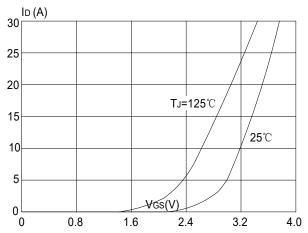


Figure 4: Body Diode Characteristics

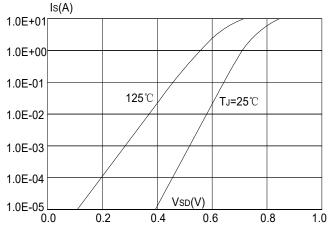
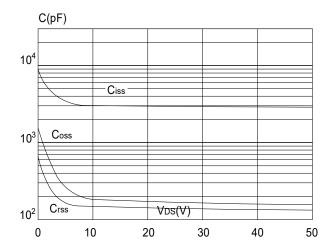


Figure 6: Capacitance Characteristics





**Figure 7:** Normalized Breakdown Voltage vs. Junction Temperature

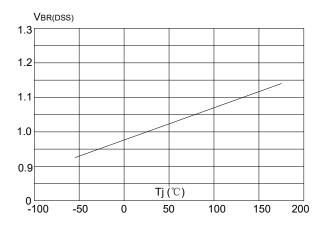


Figure 9: Maximum Safe Operating Area

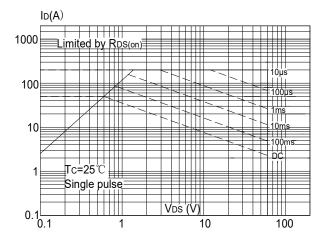
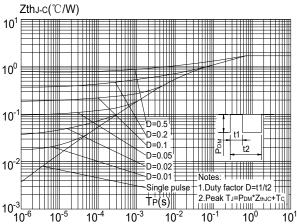
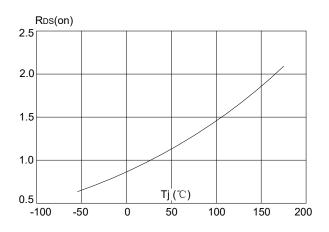


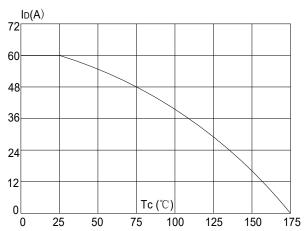
Figure.11: Maximum Effective
Transient Thermal Impedance, Junction-to-Case

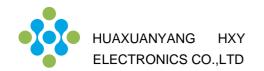


**Figure 8:** Normalized on Resistance vs. Junction Temperature

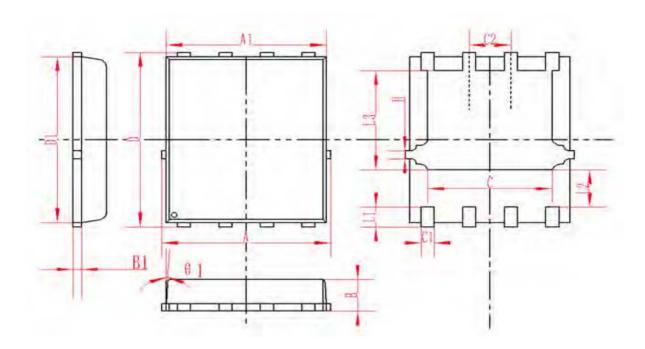


**Figure 10:** Maximum Continuous Drain Current vs. Case Temperature





# DFN5X6-8L(TDSON-8-EP(5.1x5.9)) Package Information



| SYMBOL | MM       |         | INCH     |       |        |       |
|--------|----------|---------|----------|-------|--------|-------|
|        | MIN      | NOM     | MAX      | MIN   | NOM    | MAX   |
| А      | 4.95     | 5       | 5.05     | 0.195 | 0.197  | 0.199 |
| A1     | 4.82     | 4.9     | 4.98     | 0.190 | 0.193  | 0.196 |
| D      | 5.98     | 6       | 6.02     | 0.235 | 0.236  | 0.237 |
| D1     | 5.67     | 5.75    | 5.83     | 0.223 | 0.226  | 0.230 |
| В      | 0.9      | 0.95    | 1        | 0.035 | 0.037  | 0.039 |
| B1     | 0.254REF |         | 0.010REF |       |        |       |
| С      | 3.95     | 4       | 4.05     | 0.156 | 0.157  | 0.159 |
| C1     | 0.35     | 0.4     | 0.45     | 0.014 | 0.016  | 0.018 |
| C2     |          | 1.27TYP |          |       | 0.5TYP |       |
| θ1     | 8°       | 10°     | 12°      | 8°    | 10°    | 12°   |
| L1     | 0.63     | 0.64    | 0.65     | 0.025 | 0.025  | 0.026 |
| L2     | 1.2      | 1.3     | 1.4      | 0.047 | 0.051  | 0.055 |
| L3     | 3.415    | 3.42    | 3.425    | 0.134 | 0.135  | 0.135 |
| Н      | 0.24     | 0.25    | 0.26     | 0.009 | 0.010  | 0.010 |

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